

Item	Manufacture Capabilities
Base material	FR-4 material
Pcb thickness	0.2-7.0mm
Copper thickness	0.5oz,1oz,2oz,4oz,8oz,12oz,etc.
Surface Finish	OSP,HASL lead free,ENIG,
	Immersion Tin,Immersion silver,etc.
Soldermask	Green,Yellow,Black,Blue, Red,White,Purple
Pcb type	Heavy copper power PCB,
	HDI,High multi-layer blind&buried PCB,
	Backplane,Backdrill,
	Blue glue board,etc.
Blind&buried via type	mechanical blind & burried vias with less than 2 times laminating
Hdi PCB	1+n+1,1+1+n+1+1,2+n+2,3+n+3 ("n" buried vias≤0.3mm)
aspect ratio	10:1
Min laser drilling size	4mil
Max laser drilling size	6mil
Min space between gold fingers	8mil
Finshed mechanical hole size	0.15-6.2mm (corresponding drilling tool size 0.2-6.3mm)
MAX hole size for via filled with Blue	4.5mm
Gold finger bevelling	20°,30°,45°,60°
Impedance tolerance	±5ohm(< 50ohm), ±10%(≥50ohm)